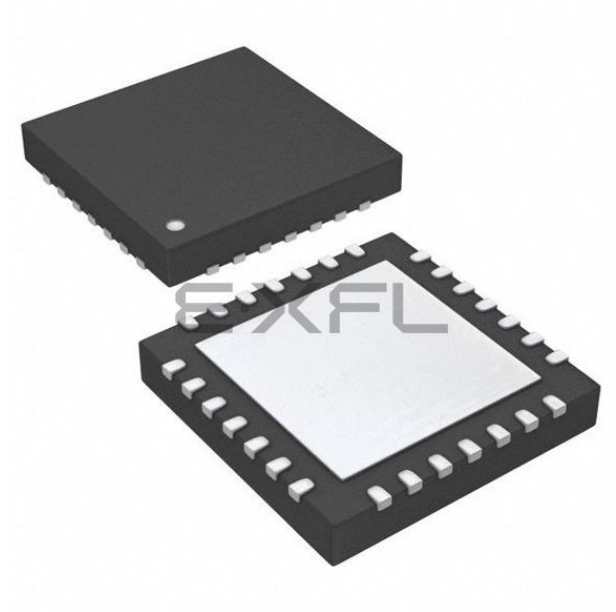

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	UART/USART, USB
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2450t-i-ml

1.0 DEVICE OVERVIEW

This document contains device-specific information for the following devices:

- PIC18F2450
- PIC18F4450

This family of devices offers the advantages of all PIC18 microcontrollers – namely, high computational performance at an economical price – with the addition of high-endurance, Enhanced Flash program memory. In addition to these features, the PIC18F2450/4450 family introduces design enhancements that make these microcontrollers a logical choice for many high-performance, power sensitive applications.

1.1 New Core Features

1.1.1 nanoWatt TECHNOLOGY

All of the devices in the PIC18F2450/4450 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- **Alternate Run Modes:** By clocking the controller from the Timer1 source or the internal RC oscillator, power consumption during code execution can be reduced by as much as 90%.
- **Multiple Idle Modes:** The controller can also run with its CPU core disabled but the peripherals still active. In these states, power consumption can be reduced even further, to as little as 4% of normal operation requirements.
- **On-the-Fly Mode Switching:** The power-managed modes are invoked by user code during operation, allowing the user to incorporate power-saving ideas into their application's software design.
- **Low Consumption in Key Modules:** The power requirements for both Timer1 and the Watchdog Timer are minimized. See **Section 21.0 "Electrical Characteristics"** for values.

1.1.2 UNIVERSAL SERIAL BUS (USB)

Devices in the PIC18F2450/4450 family incorporate a fully featured Universal Serial Bus communications module that is compliant with the USB Specification Revision 2.0. The module supports both low-speed and full-speed communication for all supported data transfer types. It also incorporates its own on-chip transceiver and 3.3V regulator and supports the use of external transceivers and voltage regulators.

1.1.3 MULTIPLE OSCILLATOR OPTIONS AND FEATURES

All of the devices in the PIC18F2450/4450 family offer twelve different oscillator options, allowing users a wide range of choices in developing application hardware. These include:

- Four Crystal modes using crystals or ceramic resonators.
- Four External Clock modes, offering the option of using two pins (oscillator input and a divide-by-4 clock output) or one pin (oscillator input, with the second pin reassigned as general I/O).
- An INTRC source (approximately 31 kHz, stable over temperature and V_{DD}). This option frees an oscillator pin for use as an additional general purpose I/O.
- A Phase Lock Loop (PLL) frequency multiplier, available to both the High-Speed Crystal and External Oscillator modes, which allows a wide range of clock speeds from 4 MHz to 48 MHz.
- Asynchronous dual clock operation, allowing the USB module to run from a high-frequency oscillator while the rest of the microcontroller is clocked from an internal low-power oscillator.

The internal oscillator provides a stable reference source that gives the family additional features for robust operation:

- **Fail-Safe Clock Monitor:** This option constantly monitors the main clock source against a reference signal provided by the internal oscillator. If a clock failure occurs, the controller is switched to the internal oscillator, allowing for continued low-speed operation or a safe application shutdown.
- **Two-Speed Start-up:** This option allows the internal oscillator to serve as the clock source from Power-on Reset, or wake-up from Sleep mode, until the primary clock source is available.

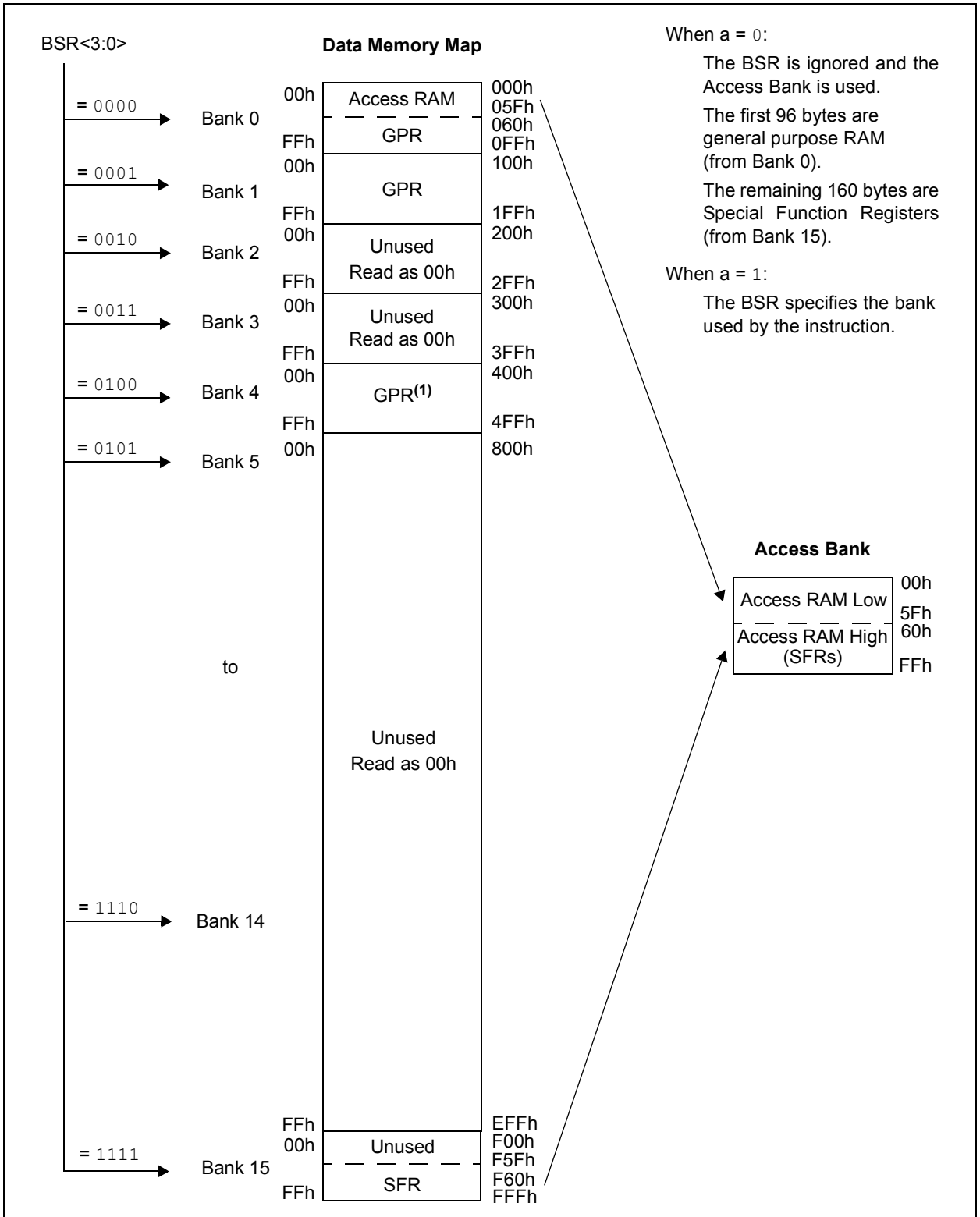
TABLE 2-3: OSCILLATOR CONFIGURATION OPTIONS FOR USB OPERATION (CONTINUED)

Input Oscillator Frequency	PLL Division (PLLDIV2:PLLDIV0)	Clock Mode (FOSC3:FOSC0)	MCU Clock Division (CPUDIV1:CPUDIV0)	Microcontroller Clock Frequency
12 MHz	÷3 (010)	HS, EC, ECIO	None (00)	12 MHz
			÷2 (01)	6 MHz
			÷3 (10)	4 MHz
			÷4 (11)	3 MHz
		HSPLL, ECPLL, ECPIO	÷2 (00)	48 MHz
			÷3 (01)	32 MHz
			÷4 (10)	**24 MHz**
			÷6 (11)	16 MHz
8 MHz	÷2 (001)	HS, EC, ECIO	None (00)	8 MHz
			÷2 (01)	4 MHz
			÷3 (10)	2.67 MHz
			÷4 (11)	2 MHz
		HSPLL, ECPLL, ECPIO	÷2 (00)	48 MHz
			÷3 (01)	32 MHz
			÷4 (10)	**24 MHz**
			÷6 (11)	16 MHz
4 MHz	÷1 (000)	XT, HS, EC, ECIO	None (00)	4 MHz
			÷2 (01)	2 MHz
			÷3 (10)	1.33 MHz
			÷4 (11)	1 MHz
		HSPLL, ECPLL, XTPLL, ECPIO	÷2 (00)	48 MHz
			÷3 (01)	32 MHz
			÷4 (10)	**24 MHz**
			÷6 (11)	16 MHz

Legend: All clock frequencies, except 24 MHz, are exclusively associated with full-speed USB operation (USB clock of 48 MHz). **Bold** is used to highlight clock selections that are compatible with low-speed USB operation (system clock of 24 MHz, USB clock of 6 MHz).

Note 1: Only valid when the USBDIV Configuration bit is cleared.

FIGURE 5-5: DATA MEMORY MAP FOR PIC18F2450/4450 DEVICES



Note 1: This bank also serve as RAM buffer for USB operation. See **Section 5.3.1 "USB RAM"** for more information.

TABLE 9-1: PORTA I/O SUMMARY

Pin	Function	TRIS Setting	I/O	I/O Type	Description
RA0/AN0	RA0	0	OUT	DIG	LATA<0> data output; not affected by analog input.
		1	IN	TTL	PORTA<0> data input; disabled when analog input enabled.
	AN0	1	IN	ANA	A/D input channel 0. Default configuration on POR; does not affect digital output.
RA1/AN1	RA1	0	OUT	DIG	LATA<1> data output; not affected by analog input.
		1	IN	TTL	PORTA<1> data input; reads '0' on POR.
	AN1	1	IN	ANA	A/D input channel 1. Default configuration on POR; does not affect digital output.
RA2/AN2/ VREF-	RA2	0	OUT	DIG	LATA<2> data output; not affected by analog input.
		1	IN	TTL	PORTA<2> data input. Disabled when analog functions enabled.
	AN2	1	IN	ANA	A/D input channel 2. Default configuration on POR; not affected by analog output.
	VREF-	1	IN	ANA	A/D voltage reference low input.
RA3/AN3/ VREF+	RA3	0	OUT	DIG	LATA<3> data output; not affected by analog input.
		1	IN	TTL	PORTA<3> data input; disabled when analog input enabled.
	AN3	1	IN	ANA	A/D input channel 3. Default configuration on POR.
	VREF+	1	IN	ANA	A/D voltage reference high input.
RA4/T0CKI/ RCV	RA4	0	OUT	DIG	LATA<4> data output; not affected by analog input.
		1	IN	ST	PORTA<4> data input; disabled when analog input enabled.
	T0CKI	1	IN	ST	Timer0 clock input.
	RCV	x	IN	TTL	External USB transceiver RCV input.
RA5/AN4/ HLVDIN	RA5	0	OUT	DIG	LATA<5> data output; not affected by analog input.
		1	IN	TTL	PORTA<5> data input; disabled when analog input enabled.
	AN4	1	IN	ANA	A/D input channel 4. Default configuration on POR.
	HLVDIN	1	IN	ANA	High/Low-Voltage Detect external trip point input.
OSC2/CLKO/ RA6	OSC2	x	OUT	ANA	Main oscillator feedback output connection (all XT and HS modes).
	CLKO	x	OUT	DIG	System cycle clock output (FOSC/4); available in EC, ECPLL and INTCKO modes.
	RA6	0	OUT	DIG	LATA<6> data output. Available only in ECIO, ECPIO and INTIO modes; otherwise, reads as '0'.
		1	IN	TTL	PORTA<6> data input. Available only in ECIO, ECPIO and INTIO modes; otherwise, reads as '0'.

Legend: OUT = Output, IN = Input, ANA = Analog Signal, DIG = Digital Output, ST = Schmitt Buffer Input, TTL = TTL Buffer Input, x = Don't care (TRIS bit does not affect port direction or is overridden for this option)

TABLE 9-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
PORTA	—	RA6(1)	RA5	RA4	RA3	RA2	RA1	RA0	51
LATA	—	LATA6(1)	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0	51
TRISA	—	TRISA6(1)	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	51
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	50
UCON	—	PPBRST	SE0	PKTDIS	USBEN	RESUME	SUSPND	—	52

Legend: — = unimplemented, read as '0'. Shaded cells are not used by PORTA.

Note 1: RA6 and its associated latch and data direction bits are enabled as I/O pins based on oscillator configuration; otherwise, they are read as '0'.

13.0 CAPTURE/COMPARE/PWM (CCP) MODULE

PIC18F2450/4450 devices have one CCP (Capture/ Compare/PWM) module. The module contains a 16-bit register, which can operate as a 16-bit Capture register, a 16-bit Compare register or a PWM Master/Slave Duty Cycle register.

REGISTER 13-1: CCP1CON: CAPTURE/COMPARE/PWM CONTROL REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DC1B1:DC1B0**: PWM Duty Cycle for CCP Module bits

Capture mode:
Unused.

Compare mode:
Unused.

PWM mode:
These bits are the two LSbs (bit 1 and bit 0) of the 10-bit PWM duty cycle. The eight MSbs of the duty cycle are found in CCPR1L.

bit 3-0 **CCP1M3:CCP1M0**: CCP Module Mode Select bits

0000 = Capture/Compare/PWM disabled (resets CCP module)
0001 = Reserved
0010 = Compare mode: toggle output on match (CCP1IF bit is set)
0011 = Reserved
0100 = Capture mode: every falling edge
0101 = Capture mode: every rising edge
0110 = Capture mode: every 4th rising edge
0111 = Capture mode: every 16th rising edge
1000 = Compare mode: initialize CCP1 pin low; on compare match, force CCP1 pin high (CCP1IF bit is set)
1001 = Compare mode: initialize CCP1 pin high; on compare match, force CCP1 pin low (CCP1IF bit is set)
1010 = Compare mode: generate software interrupt on compare match (CCP1IF bit is set, CCP1 pin reflects I/O state)
1011 = Compare mode: trigger special event, reset timer and start A/D conversion on CCP1 match (CCP1IF bit is set)
11xx = PWM mode

14.4 Buffer Descriptors and the Buffer Descriptor Table

The registers in Bank 4 are used specifically for endpoint buffer control in a structure known as the Buffer Descriptor Table (BDT). This provides a flexible method for users to construct and control endpoint buffers of various lengths and configuration.

The BDT is composed of Buffer Descriptors (BD) which are used to define and control the actual buffers in the USB RAM space. Each BD, in turn, consists of four registers, where n represents one of the 64 possible BDs (range of 0 to 63):

- BDnSTAT: BD Status register
- BDnCNT: BD Byte Count register
- BDnADRL: BD Address Low register
- BDnADRH: BD Address High register

BDs always occur as a four-byte block in the sequence, BDnSTAT:BDnCNT:BDnADRL:BDnADRH. The address of BDnSTAT is always an offset of (4n – 1) (in hexadecimal) from 400h, with n being the buffer descriptor number.

Depending on the buffering configuration used (**Section 14.4.4 "Ping-Pong Buffering"**), there are up to 32, 33 or 64 sets of buffer descriptors. At a minimum, the BDT must be at least 8 bytes long. This is because the USB specification mandates that every device must have Endpoint 0 with both input and output for initial setup. Depending on the endpoint and buffering configuration, the BDT can be as long as 256 bytes.

Although they can be thought of as Special Function Registers, the Buffer Descriptor Status and Address registers are not hardware mapped, as conventional microcontroller SFRs in Bank 15 are. If the endpoint corresponding to a particular BD is not enabled, its registers are not used. Instead of appearing as unimplemented addresses, however, they appear as available RAM. Only when an endpoint is enabled by setting the UEPn<1> bit does the memory at those addresses become functional as BD registers. As with any address in the data memory space, the BD registers have an indeterminate value on any device Reset.

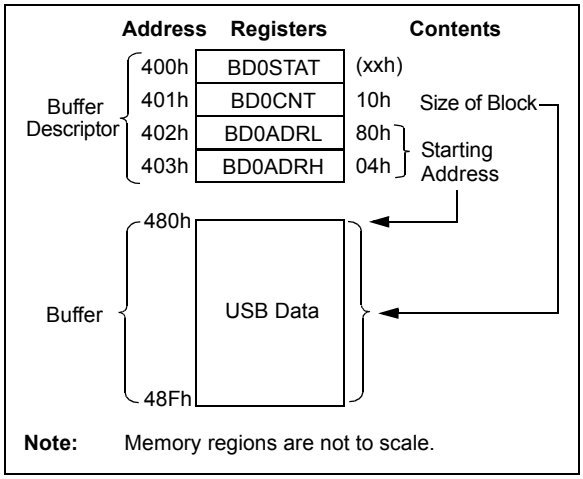
A total of 256 bytes of address space in Bank 4 is available for BDT and USB data RAM. In Ping-Pong Buffer mode, all the 16 bidirectional endpoints can not be implemented where BDT itself can be as long as 256 bytes. In the majority of USB applications, few endpoints are required to be implemented. Hence, a small portion of the 256 bytes will be used for BDT and the rest can be used for USB data.

An example of a BD for a 16-byte buffer, starting at 480h, is shown in Figure 14-6. A particular set of BD registers is only valid if the corresponding endpoint has been enabled using the UEPn register. All BD registers are available in USB RAM. The BD for each endpoint should be set up prior to enabling the endpoint.

14.4.1 BD STATUS AND CONFIGURATION

Buffer descriptors not only define the size of an endpoint buffer, but also determine its configuration and control. Most of the configuration is done with the BD Status register, BDnSTAT. Each BD has its own unique and correspondingly numbered BDnSTAT register.

FIGURE 14-6: EXAMPLE OF A BUFFER DESCRIPTOR



Note: Memory regions are not to scale.

Unlike other control registers, the bit configuration for the BDnSTAT register is context sensitive. There are two distinct configurations, depending on whether the microcontroller or the USB module is modifying the BD and buffer at a particular time. Only three bit definitions are shared between the two.

14.4.1.1 Buffer Ownership

Because the buffers and their BDs are shared between the CPU and the USB module, a simple semaphore mechanism is used to distinguish which is allowed to update the BD and associated buffers in memory.

This is done by using the UOWN bit (BDnSTAT<7>) as a semaphore to distinguish which is allowed to update the BD and associated buffers in memory. UOWN is the only bit that is shared between the two configurations of BDnSTAT.

When UOWN is clear, the BD entry is "owned" by the microcontroller core. When the UOWN bit is set, the BD entry and the buffer memory are "owned" by the USB peripheral. The core should not modify the BD or its corresponding data buffer during this time. Note that the microcontroller core can still read BDnSTAT while the SIE owns the buffer and vice versa.

The buffer descriptors have a different meaning based on the source of the register update. Prior to placing ownership with the USB peripheral, the user can configure the basic operation of the peripheral through the BDnSTAT bits. During this time, the byte count and buffer location registers can also be set.

14.6 USB Power Modes

Many USB applications will likely have several different sets of power requirements and configuration. The most common power modes encountered are Bus Power Only, Self-Power Only and Dual Power with Self-Power Dominance. The most common cases are presented here.

14.6.1 BUS POWER ONLY

In Bus Power Only mode, all power for the application is drawn from the USB (Figure 14-10). This is effectively the simplest power method for the device.

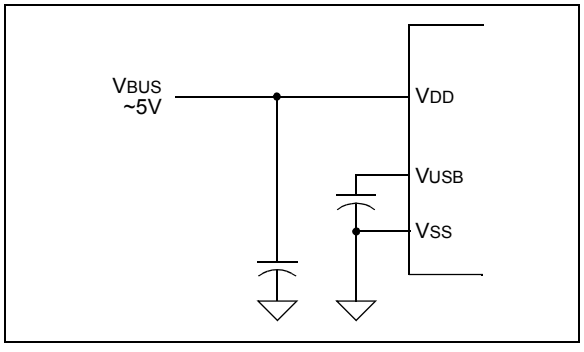
In order to meet the inrush current requirements of the USB 2.0 specifications, the total effective capacitance appearing across VBUS and ground must be no more than 10 μF; otherwise, some kind of inrush limiting is required. For more details, see Section 7.2.4 of the USB 2.0 specification.

According to the USB 2.0 specification, all USB devices must also support a Low-Power Suspend mode. In the USB Suspend mode, devices must consume no more than 500 A (or 2.5 mA for high-powered devices that are capable of remote wake-up) from the 5V VBUS line of the USB cable.

The host signals the USB device to enter the Suspend mode by stopping all USB traffic to that device for more than 3 ms. This condition will set the IDLEIF bit in the UIR register.

During the USB Suspend mode, the D+ or D- pull-up resistor must remain active, which will consume some of the allowed suspend current: 500A/2.5 mA budget.

FIGURE 14-10: BUS POWER ONLY



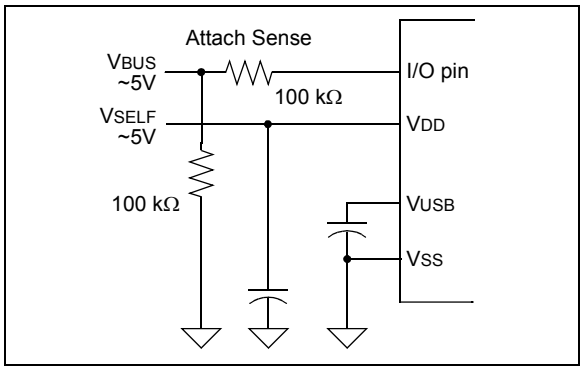
14.6.2 SELF-POWER ONLY

In Self-Power Only mode, the USB application provides its own power, with very little power being pulled from the USB. Figure 14-11 shows an example. Note that an attach indication is added to show when the USB has been connected and the host is actively powering VBUS.

In order to meet compliance specifications, the USB module (and the D+ or D- pull-up resistor) should not be enabled until the host actively drives VBUS high. One of the I/O pins may be used for this purpose.

The application should never source any current onto the 5V VBUS pin of the USB cable.

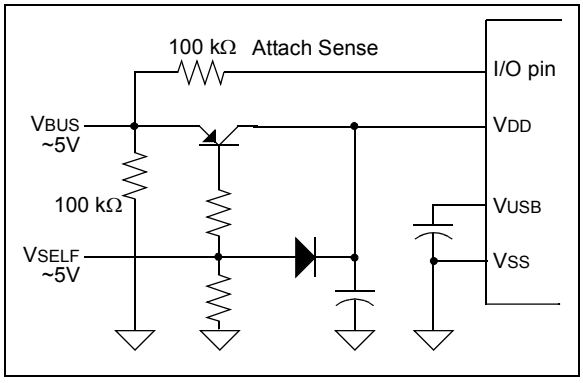
FIGURE 14-11: SELF-POWER ONLY



14.6.3 DUAL POWER WITH SELF-POWER DOMINANCE

Some applications may require a dual power option. This allows the application to use internal power primarily, but switch to power from the USB when no internal power is available. Figure 14-12 shows a simple Dual Power with Self-Power Dominance example, which automatically switches between Self-Power Only and USB Bus Power Only modes.

FIGURE 14-12: DUAL POWER EXAMPLE



Dual power devices must also meet all of the special requirements for inrush current and Suspend mode current, and must not enable the USB module until VBUS is driven high. For descriptions of those requirements, see **Section 14.6.1 "Bus Power Only"** and **Section 14.6.2 "Self-Power Only"**. Additionally, dual power devices must never source current onto the 5V VUSB pin of the USB cable.

Note:	Users should keep in mind the limits for devices drawing power from the USB. According to USB Specification 2.0, this cannot exceed 100 mA per low-power device or 500 mA per high-power device.

TABLE 15-3: BAUD RATES FOR ASYNCHRONOUS MODES

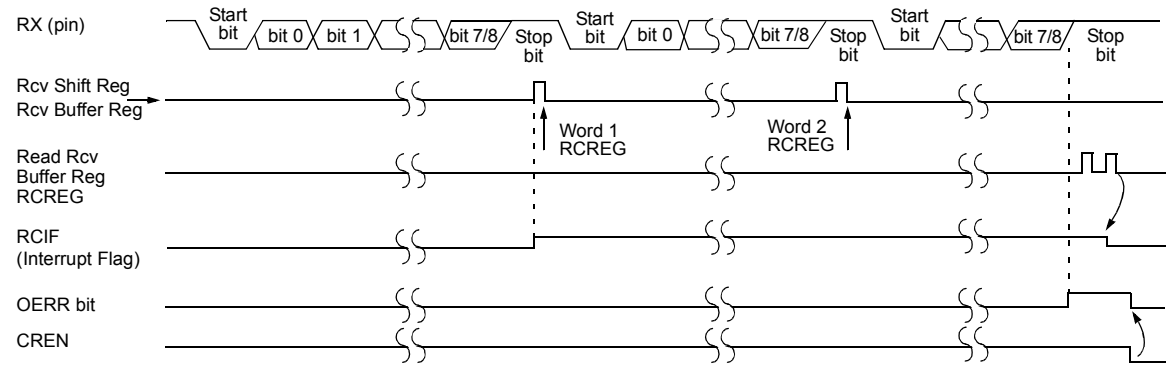
BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 0											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	—	—	—	—	—	—
1.2	—	—	—	1.221	1.73	255	1.202	0.16	129	1.201	-0.16	103
2.4	2.441	1.73	255	2.404	0.16	129	2.404	0.16	64	2.403	-0.16	51
9.6	9.615	0.16	64	9.766	1.73	31	9.766	1.73	15	9.615	-0.16	12
19.2	19.531	1.73	31	19.531	1.73	15	19.531	1.73	7	—	—	—
57.6	56.818	-1.36	10	62.500	8.51	4	52.083	-9.58	2	—	—	—
115.2	125.000	8.51	4	104.167	-9.58	2	78.125	-32.18	1	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 0								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.16	207	0.300	-0.16	103	0.300	-0.16	51
1.2	1.202	0.16	51	1.201	-0.16	25	1.201	-0.16	12
2.4	2.404	0.16	25	2.403	-0.16	12	—	—	—
9.6	8.929	-6.99	6	—	—	—	—	—	—
19.2	20.833	8.51	2	—	—	—	—	—	—
57.6	62.500	8.51	0	—	—	—	—	—	—
115.2	62.500	-45.75	0	—	—	—	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 0											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	—	—	—	—	—	—
1.2	—	—	—	—	—	—	—	—	—	—	—	—
2.4	—	—	—	—	—	—	2.441	1.73	255	2.403	-0.16	207
9.6	9.766	1.73	255	9.615	0.16	129	9.615	0.16	64	9.615	-0.16	51
19.2	19.231	0.16	129	19.231	0.16	64	19.531	1.73	31	19.230	-0.16	25
57.6	58.140	0.94	42	56.818	-1.36	21	56.818	-1.36	10	55.555	3.55	8
115.2	113.636	-1.36	21	113.636	-1.36	10	125.000	8.51	4	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 0								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	0.300	-0.16	207
1.2	1.202	0.16	207	1.201	-0.16	103	1.201	-0.16	51
2.4	2.404	0.16	103	2.403	-0.16	51	2.403	-0.16	25
9.6	9.615	0.16	25	9.615	-0.16	12	—	—	—
19.2	19.231	0.16	12	—	—	—	—	—	—
57.6	62.500	8.51	3	—	—	—	—	—	—
115.2	125.000	8.51	1	—	—	—	—	—	—

FIGURE 15-7: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX input. The RCREG (Receive Buffer) is read after the third word causing the OERR (Overrun Error) bit to be set.

TABLE 15-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	49
PIR1	—	ADIF	RCIF	TXIF	—	CCP1IF	TMR2IF	TMR1IF	51
PIE1	—	ADIE	RCIE	TXIE	—	CCP1IE	TMR2IE	TMR1IE	51
IPR1	—	ADIP	RCIP	TXIP	—	CCP1IP	TMR2IP	TMR1IP	51
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	51
RCREG	EUSART Receive Register								50
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	51
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	51
SPBRGH	EUSART Baud Rate Generator Register High Byte								50
SPBRG	EUSART Baud Rate Generator Register Low Byte								50

Legend: — = unimplemented locations read as '0'. Shaded cells are not used for asynchronous reception.

The module is enabled by setting the HLVDEN bit. Each time that the HLVD module is enabled, the circuitry requires some time to stabilize. The IRVST bit is a read-only bit and is used to indicate when the circuit is stable. The module can only generate an interrupt after the circuit is stable and IRVST is set.

The VDIRMAG bit determines the overall operation of the module. When VDIRMAG is cleared, the module monitors for drops in VDD below a predetermined set point. When the bit is set, the module monitors for rises in VDD above the set point.

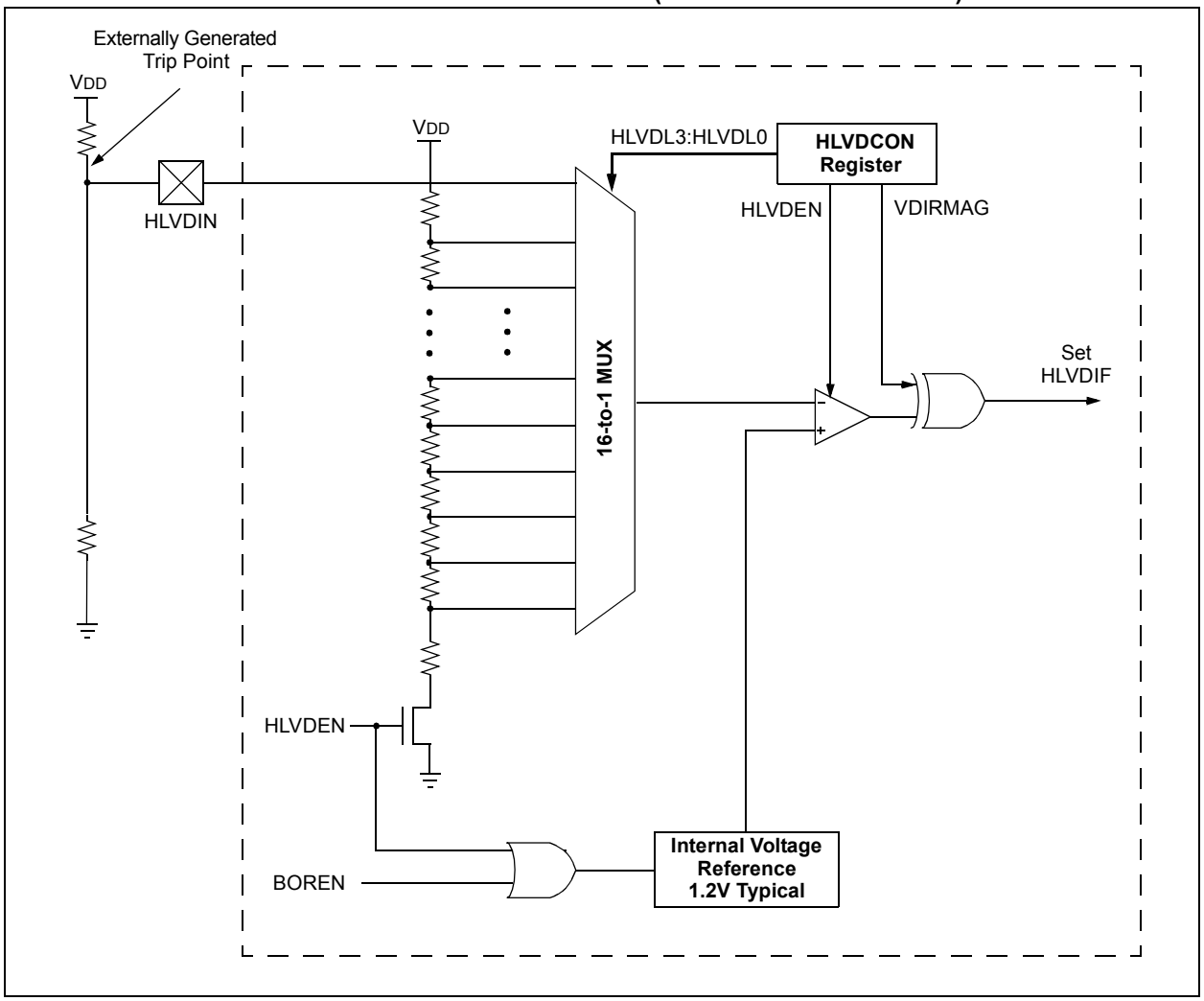
17.1 Operation

When the HLVD module is enabled, a comparator uses an internally generated reference voltage as the set point. The set point is compared with the trip point, where each node in the resistor divider represents a trip point voltage. The “trip point” voltage is the voltage level at which the device detects a high or low-voltage event, depending on the configuration of the module. When the supply voltage is equal to the trip point, the voltage tapped off of the resistor array is equal to the internal reference voltage generated by the voltage reference module. The comparator then generates an interrupt signal by setting the HLVDIF bit.

The trip point voltage is software programmable to any one of 16 values. The trip point is selected by programming the HLVDL3:HLVDL0 bits (HLVDCON<3:0>).

The HLVD module has an additional feature that allows the user to supply the trip voltage to the module from an external source. This mode is enabled when bits, HLVDL3:HLVDL0, are set to ‘1111’. In this state, the comparator input is multiplexed from the external input pin, HLVDIN. This gives users flexibility because it allows them to configure the High/Low-Voltage Detect interrupt to occur at any voltage in the valid operating range.

FIGURE 17-1: HLVD MODULE BLOCK DIAGRAM (WITH EXTERNAL INPUT)



17.2 HLVD Setup

The following steps are needed to set up the HLVD module:

1. Disable the module by clearing the HLVDEN bit (HLVDCON<4>).
2. Write the value to the HLVDL3:HLVDL0 bits that selects the desired HLVD trip point.
3. Set the VDIRMAG bit to detect high voltage (VDIRMAG = 1) or low voltage (VDIRMAG = 0).
4. Enable the HLVD module by setting the HLVDEN bit.
5. Clear the HLVD Interrupt Flag, HLVDIF (PIR2<2>), which may have been set from a previous interrupt.
6. Enable the HLVD interrupt, if interrupts are desired, by setting the HLVDIE and GIE/GIEH bits (PIE2<2> and INTCON<7>). An interrupt will not be generated until the IRVST bit is set.

17.3 Current Consumption

When the module is enabled, the HLVD comparator and voltage divider are enabled and will consume static current. The total current consumption, when enabled, is specified in electrical specification parameter D022 (**Section 270 "DC Characteristics"**).

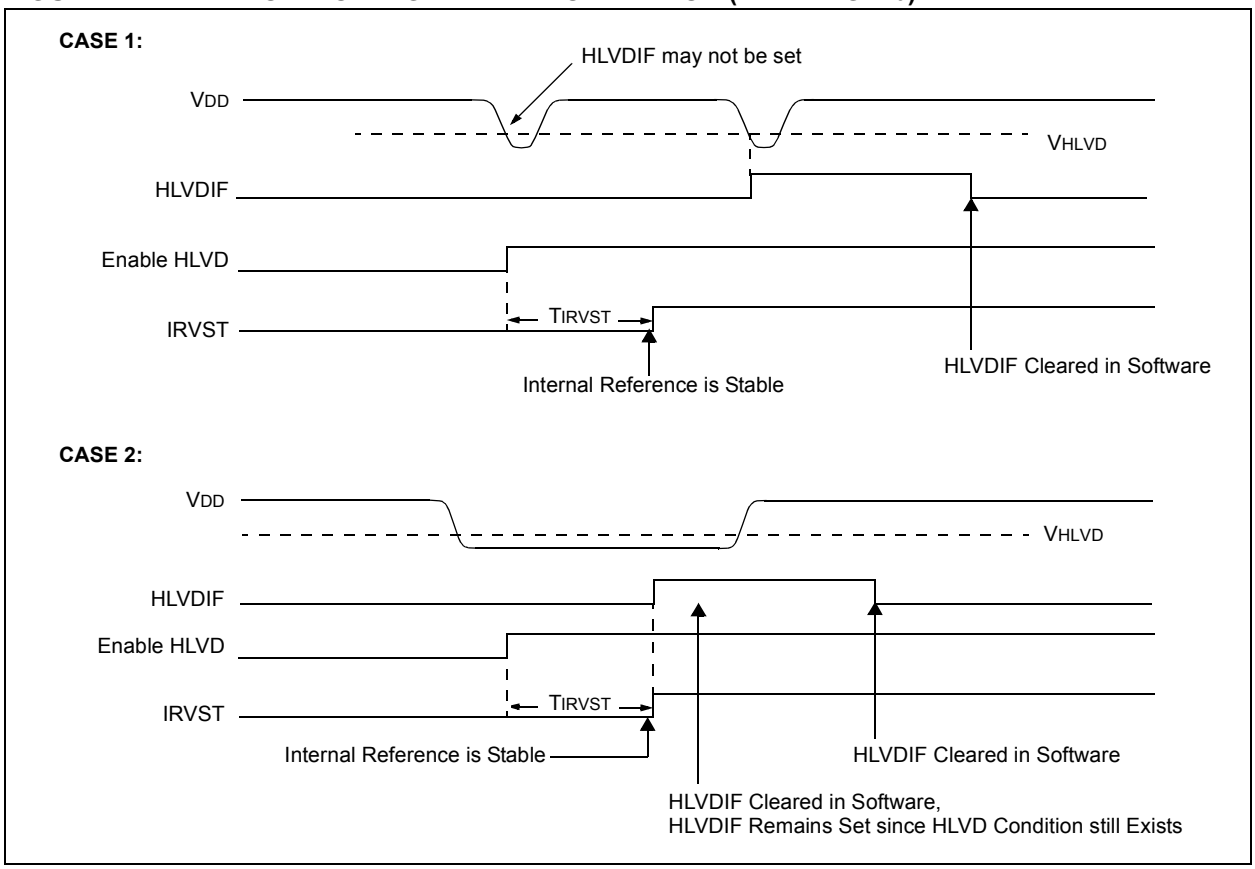
Depending on the application, the HLVD module does not need to be operating constantly. To decrease the current requirements, the HLVD circuitry may only need to be enabled for short periods where the voltage is checked. After doing the check, the HLVD module may be disabled.

17.4 HLVD Start-up Time

The internal reference voltage of the HLVD module, specified in electrical specification parameter D420 (see Table 21-4 in **Section 21.0 "Electrical Characteristics"**), may be used by other internal circuitry, such as the Programmable Brown-out Reset. If the HLVD or other circuits using the voltage reference are disabled to lower the device's current consumption, the reference voltage circuit will require time to become stable before a low or high-voltage condition can be reliably detected. This start-up time, TIRVST, is an interval that is independent of device clock speed. It is specified in electrical specification parameter 36 (Table 21-10).

The HLVD interrupt flag is not enabled until TIRVST has expired and a stable reference voltage is reached. For this reason, brief excursions beyond the set point may not be detected during this interval. Refer to Figure 17-2 or Figure 17-3.

FIGURE 17-2: LOW-VOLTAGE DETECT OPERATION (VDIRMAG = 0)



REGISTER 18-2: CONFIG1H: CONFIGURATION REGISTER 1 HIGH (BYTE ADDRESS 300001h)

R/P-0	R/P-0	U-0	U-0	R/P-0	R/P-1	R/P-1	R/P-1
IESO	FCMEN	—	—	FOSC3(1)	FOSC2(1)	FOSC1(1)	FOSC0(1)
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7 **IESO:** Internal/External Oscillator Switchover bit
1 = Oscillator Switchover mode enabled
0 = Oscillator Switchover mode disabled

bit 6 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor enabled
0 = Fail-Safe Clock Monitor disabled

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **FOSC3:FOSC0:** Oscillator Selection bits(1)
111x = HS oscillator, PLL enabled (HSPLL)
110x = HS oscillator (HS)
1011 = Internal oscillator, HS oscillator used by USB (INTHS)
1010 = Internal oscillator, XT used by USB (INTXT)
1001 = Internal oscillator, CLKO function on RA6, EC used by USB (INTCKO)
1000 = Internal oscillator, port function on RA6, EC used by USB (INTIO)
0111 = EC oscillator, PLL enabled, CLKO function on RA6 (ECPLL)
0110 = EC oscillator, PLL enabled, port function on RA6 (ECPIO)
0101 = EC oscillator, CLKO function on RA6 (EC)
0100 = EC oscillator, port function on RA6 (ECIO)
001x = XT oscillator, PLL enabled (XTPLL)
000x = XT oscillator (XT)

Note 1: The microcontroller and USB module both use the selected oscillator as their clock source in XT, HS and EC modes. The USB module uses the indicated XT, HS or EC oscillator as its clock source whenever the microcontroller uses the internal oscillator.

REGISTER 18-3: CONFIG2L: CONFIGURATION REGISTER 2 LOW (BYTE ADDRESS 300002h)

U-0	U-0	R/P-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
—	—	VREGEN	BORV1(1)	BORV0(1)	BOREN1(2)	BOREN0(2)	$\overline{\text{PWRTEN}}$(2)
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **VREGEN:** USB Internal Voltage Regulator Enable bit
1 = USB voltage regulator enabled
0 = USB voltage regulator disabled

bit 4-3 **BORV1:BORV0:** Brown-out Reset Voltage bits(1)
11 = Minimum setting
.
.
.
00 = Maximum setting

bit 2-1 **BOREN1:BOREN0:** Brown-out Reset Enable bits(2)
11 = Brown-out Reset enabled in hardware only (SBOREN is disabled)
10 = Brown-out Reset enabled in hardware only and disabled in Sleep mode (SBOREN is disabled)
01 = Brown-out Reset enabled and controlled by software (SBOREN is enabled)
00 = Brown-out Reset disabled in hardware and software

bit 0 **$\overline{\text{PWRTEN}}$:** Power-up Timer Enable bit(2)
1 = PWRT disabled
0 = PWRT enabled

Note 1: See **Section 21.0 "Electrical Characteristics"** for the specifications.

2: The Power-up Timer is decoupled from Brown-out Reset, allowing these features to be independently controlled.

REGISTER 18-9: CONFIG6L: CONFIGURATION REGISTER 6 LOW (BYTE ADDRESS 30000Ah)

U-0	U-0	U-0	U-0	U-0	U-0	R/C-1	R/C-1
—	—	—	—	—	—	WRT1	WRT0
bit 7							bit 0

Legend:		
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **WRT1:** Write Protection bit
1 = Block 1 (002000-003FFFh) is not write-protected
0 = Block 1 (002000-003FFFh) is write-protected

bit 0 **WRT0:** Write Protection bit
1 = Block 0 (000800-001FFFh) or (001000-001FFFh) is not write-protected
0 = Block 0 (000800-001FFFh) or (001000-001FFFh) is write-protected

REGISTER 18-10: CONFIG6H: CONFIGURATION REGISTER 6 HIGH (BYTE ADDRESS 30000Bh)

U-0	R/C-1	R-1	U-0	U-0	U-0	U-0	U-0
—	WRTB	WRTC(1)	—	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7 **Unimplemented:** Read as '0'

bit 6 **WRTB:** Boot Block Write Protection bit
1 = Boot block (000000-0007FFh) or (000000-000FFFh) is not write-protected
0 = Boot block (000000-0007FFh) or (000000-000FFFh) is write-protected

bit 5 **WRTC:** Configuration Register Write Protection bit(1)
1 = Configuration registers (300000-3000FFh) are not write-protected
0 = Configuration registers (300000-3000FFh) are write-protected

bit 4-0 **Unimplemented:** Read as '0'

Note 1: This bit is read-only in normal execution mode; it can be written only in Program mode.

REGISTER 18-13: DEVID1: DEVICE ID REGISTER 1 FOR PIC18F2450/4450 DEVICES

R	R	R	R	R	R	R	R
DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0
bit 7							bit 0

Legend:		
R = Read-only bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7-5 **DEV2:DEV0:** Device ID bits
001 = PIC18F2450
000 = PIC18F4450

bit 4-0 **REV4:REV0:** Revision ID bits
These bits are used to indicate the device revision.

REGISTER 18-14: DEVID2: DEVICE ID REGISTER 2 FOR PIC18F2450/4450 DEVICES

R	R	R	R	R	R	R	R
DEV10(1)	DEV9(1)	DEV8(1)	DEV7(1)	DEV6(1)	DEV5(1)	DEV4(1)	DEV3(1)
bit 7							bit 0

Legend:		
R = Read-only bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7-0 **DEV10:DEV3:** Device ID bits(1)
These bits are used with the DEV2:DEV0 bits in the DEVID1 register to identify the part number.
0010 0100 = PIC18F2450/4450 devices

Note 1: These values for DEV10:DEV3 may be shared with other devices. The specific device is always identified by using the entire DEV10:DEV0 bit sequence.

CLRF **Clear f**

Syntax: CLRF f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: 000h → f,
1 → Z

Status Affected: Z

Encoding:

0110	101a	ffff	ffff

Description: Clears the contents of the specified register.
If 'a' is '0', the Access Bank is selected.
If 'a' is '1', the BSR is used to select the GPR bank (default).
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 19.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: CLRF FLAG_REG,1

Before Instruction
FLAG_REG = 5Ah
After Instruction
FLAG_REG = 00h

CLRWDT **Clear Watchdog Timer**

Syntax: CLRWDT

Operands: None

Operation: 000h → WDT,
000h → WDT postscaler,
1 → $\overline{TO}$,
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

0000	0000	0000	0100

Description: CLRWDT instruction resets the Watchdog Timer. It also resets the postscaler of the WDT. Status bits, $\overline{TO}$ and $\overline{PD}$, are set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	Process Data	No operation

Example: CLRWDT

Before Instruction
WDT Counter = ?
After Instruction
WDT Counter = 00h
WDT Postscaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

21.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +85°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0V to +13.25V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports ..... 200 mA

Note 1: Power dissipation is calculated as follows:
Pdis = V_{DD} x {I_{DD} – ∑ I_{OH}} + ∑ {(V_{DD} – V_{OH}) x I_{OH}} + ∑(V_{OL} x I_{OL})

2: Voltage spikes below V_{SS} at the $\overline{MCLR}$/V_{PP}/RE3 pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{MCLR}$/V_{PP}/RE3 pin, rather than pulling this pin directly to V_{SS}.

† **NOTICE:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 21-1: MEMORY PROGRAMMING REQUIREMENTS

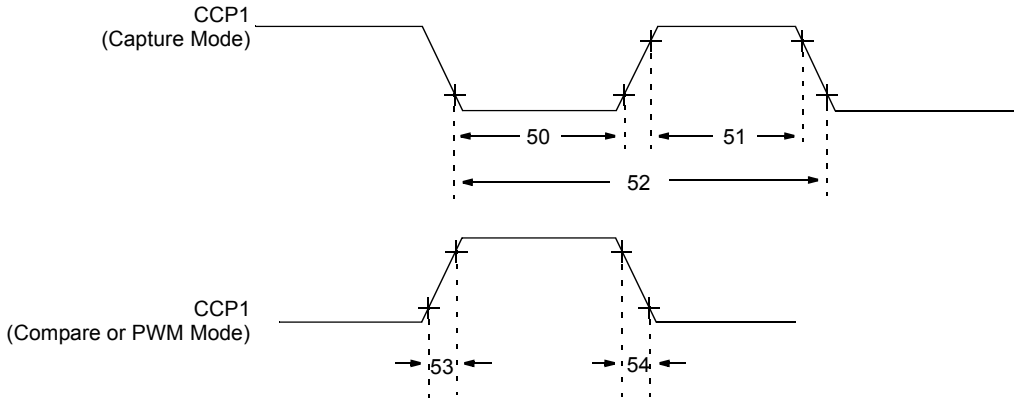
DC Characteristics			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Internal Program Memory Programming Specifications(1)					
D110	VIHH	Voltage on $\overline{\text{MCLR}}$/VPP/RE3 pin	9.00	—	13.25	V	**(Note 2)**
D113	IDDP	Supply Current during Programming	—	—	10	mA	
		Program Flash Memory					
D130	EP	Cell Endurance	10K	100K	—	E/W	-40°C to +85°C
D131	VPR	VDD for Read	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D132	VIE	VDD for Block Erase	4.5	—	5.5	V	Using ICSP™ port
D132A	VIW	VDD for Externally Timed Erase or Write	3.0	—	5.5	V	Using ICSP port
D132B	VPEW	VDD for Self-Timed Write	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D133	TIE	ICSP™ Block Erase Cycle Time	—	4	—	ms	VDD > 4.5V
D133A	TIW	ICSP Erase or Write Cycle Time (externally timed)	1	—	—	ms	VDD > 4.5V
D133A	TIW	Self-Timed Write Cycle Time	—	2	—	ms	
D134	TRETD	Characteristic Retention	40	100	—	Year	Provided no other specifications are violated

† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: These specifications are for programming the on-chip program memory through the use of table write instructions.

2: Required only if Single-Supply Programming is disabled.

FIGURE 21-10: CAPTURE/COMPARE/PWM TIMINGS (CCP MODULE)



Note: Refer to Figure 21-4 for load conditions.

TABLE 21-12: CAPTURE/COMPARE/PWM REQUIREMENTS

Param No.	Symbol	Characteristic			Min	Max	Units	Conditions
50	TccL	CCP1 Input Low Time	No prescaler		0.5 TCY + 20	—	ns	
			With prescaler	PIC18**F**XXXX	10	—	ns	
				PIC18**LF**XXXX	20	—	ns	VDD = 2.0V
51	TccH	CCP1 Input High Time	No prescaler		0.5 TCY + 20	—	ns	
			With prescaler	PIC18**F**XXXX	10	—	ns	
				PIC18**LF**XXXX	20	—	ns	VDD = 2.0V
52	TccP	CCP1 Input Period			$\frac{3\ T_{CY} + 40}{N}$	—	ns	N = prescale value (1, 4 or 16)
53	TccR	CCP1 Output Fall Time		PIC18**F**XXXX	—	25	ns	
				PIC18**LF**XXXX	—	45	ns	VDD = 2.0V
54	TccF	CCP1 Output Fall Time		PIC18**F**XXXX	—	25	ns	
				PIC18**LF**XXXX	—	45	ns	VDD = 2.0V

TABLE 21-18: A/D CONVERSION REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
130	TAD	A/D Clock Period	PIC18**F**XXXX	0.7	25(1)	µs	TOSC based, VREF ≥ 3.0V
			PIC18**LF**XXXX	1.4	25(1)	µs	VDD = 2.0V, TOSC based, VREF full range
			PIC18**F**XXXX	2.0	6.0	µs	A/D RC mode
			PIC18**LF**XXXX	3.0	9.0	µs	VDD = 2.0V, A/D RC mode
131	TCNV	Conversion Time (not including acquisition time)(2)		11	12	TAD	
132	TACQ	Acquisition Time(3)		15 10	— —	µs µs	-40°C to +85°C 0°C ≤ to ≤ +85°C
135	TSWC	Switching Time from Convert → Sample		—	**(Note 4)**		
137	TDIS	Discharge Time		0.2	—	µs	

Note 1: The time of the A/D clock period is dependent on the device frequency and the TAD clock divider.

2: ADRES registers may be read on the following TCY cycle.

3: The time for the holding capacitor to acquire the “New” input voltage when the voltage changes full scale after the conversion (VDD to VSS or VSS to VDD). The source impedance (RS) on the input channels is 50Ω.

4: On the following cycle of the device clock.